



Evyap Sabun Malaysia Sdn Bhd

Evyap Oleo LIV Coconut FA

(Low IV Topped Coconut Fatty Acid)

Product Code: DLT 300

Product Data Sheet

CAS No. 67701-05-7

EINECS No. 266-929-0

Parameter	Unit	Specification
Appearance at 40 Deg. C	-	Clear liquid, free from foreign matter.
Colour, Lovibond, Max	In 5, ¼" Cell	Y=2.0; R=0.3
Acid Value	mg KOH/Gm	250-260
Sap. Value	mg KOH/Gm	251-261
Iodine Value	Gm I ₂ / 100 Gm	1.0 Max.
Titre, Min	° C	28 -32

Fatty Acid Composition	Unit	Specification
Up to C 10	% by GC	1.0 Max.
C 12	% by GC	50 - 56
C 14	% by GC	18 - 25
C 16	% by GC	8 - 13
C 18	% by GC	8 - 15
C 18:1	% by GC	1.0 Max.
Others	% by GC	1.0

The above chart indicates typical available specifications. Customised specifications are also available.

APPLICATIONS

Preparation of food ingredients, cosmetics and personal care products, surfactant manufacture, soap noodles, industrial application like coatings and fabric softener.

PACKING

Available in standard 180kg HDPE / MS drums, road tankers or bulk ISO container loads. Customised packing size can be made available upon request.

BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

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